HEF4049B

Hex inverting buffers

Rev. 10 — 24 March 2016 **Product data sheet**

1. General description

The HEF4049B provides six inverting buffers with high current output capability suitable for driving TTL or high capacitive loads. Since input voltages in excess of the buffers' supply voltage are permitted, the buffers may also be used to convert logic levels of up to 15 V to standard TTL levels. Their guaranteed fan-out into common bipolar logic elements is shown in Table 3.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD}, V_{SS}, or another input.

2. Features and benefits

- Accepts input voltages in excess of the supply voltage
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from –40 °C to +85 °C
- Complies with JEDEC standard JESD 13-B

3. Applications

- LOCMOS (Local Oxidation CMOS) to DTL/TTL converter
- HIGH sink current for driving two TTL loads
- HIGH-to-LOW level logic conversion

4. Ordering information

Table 1. Ordering information

All types operate from –40 °C to +85 °C.

Type number	Package		
	Name	Description	Version
HEF4049BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

5. Functional diagram

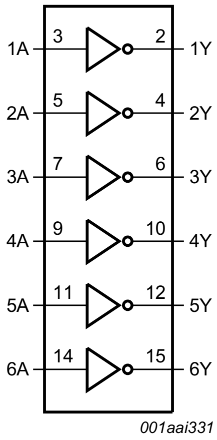


Fig 1. Logic symbol

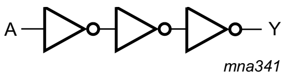


Fig 2. Logic diagram for one gate

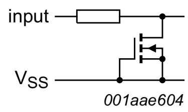


Fig 3. Input protection circuit

6. Pinning information

6.1 Pinning

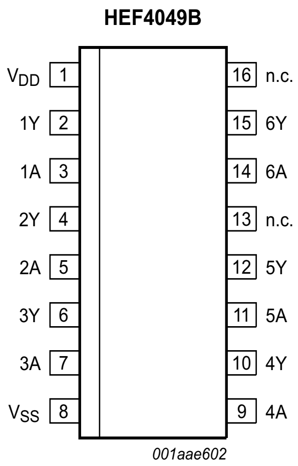


Fig 4. Pin configuration

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V_{DD}	1	supply voltage
1Y to 6Y	2, 4, 6, 10, 12, 15	output
1A to 6A	3, 5, 7, 9, 11, 14	input
V_{SS}	8	ground supply voltage
n.c.	13, 16	not connected

7. Functional description

Table 3. Guaranteed fan-out

Driven element	Guaranteed fan-out
Standard TTL	2
74 LS	9
74 L	16

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		–0.5	+18	V
I_{IK}	input clamping current	V_I < –0.5 V or V_I > V_{DD} + 0.5 V	-	±10	mA
V_I	input voltage		–0.5	V_{DD} + 0.5	V
I_{OK}	output clamping current	V_O < –0.5 V or V_O > V_{DD} + 0.5 V	-	±10	mA
$I_{I/O}$	input/output current		-	±10	mA
I_{DD}	supply current		-	50	mA
T_{stg}	storage temperature		–65	+150	°C
T_{amb}	ambient temperature		–40	+85	°C
P_{tot}	total power dissipation	T_{amb} –40 °C to +85 °C			
		SO16 package [1]	-	500	mW
P	power dissipation	per output	-	100	mW

[1] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	supply voltage		3	-	15	V
V_I	input voltage		0	-	V_{DD}	V
T_{amb}	ambient temperature	in free air	–40	-	+85	°C
Δt/ΔV	input transition rise and fall rate	V_{DD} = 5 V	-	-	3.75	μs/V
		V_{DD} = 10 V	-	-	0.5	μs/V
		V_{DD} = 15 V	-	-	0.08	μs/V

10. Static characteristics

Table 6. Static characteristics

V_{SS} = 0 V; V_I = V_{SS} or V_{DD} unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	T_{amb} = –40 °C		T_{amb} = 25 °C		T_{amb} = 85 °C		Unit
				Min	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$\|I_O\|$ < 1 μA	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
V_{IL}	LOW-level input voltage	$\|I_O\|$ < 1 μA	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V

Table 6. Static characteristics *...continued*
V_{SS} = 0 V; V_I = V_{SS} or V_{DD} unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	T_{amb} = –40 °C		T_{amb} = 25 °C		T_{amb} = 85 °C		Unit
				Min	Max	Min	Max	Min	Max	
V_{OH}	HIGH-level output voltage	$\lvert I_O \rvert < 1$ μA	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
V_{OL}	LOW-level output voltage	$\lvert I_O \rvert < 1$ μA	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
I_{OH}	HIGH-level output current	V_O = 2.5 V	5 V	-	–1.7	-	–1.4	-	–1.1	mA
		V_O = 4.6 V	5 V	-	–0.52	-	–0.44	-	–0.36	mA
		V_O = 9.5 V	10 V	-	–1.3	-	–1.1	-	–0.9	mA
		V_O = 13.5 V	15 V	-	–3.6	-	–3.0	-	–2.4	mA
I_{OL}	LOW-level output current	V_O = 0.4 V	4.75 V	3.5	-	2.9	-	2.3	-	mA
		V_O = 0.5 V	10 V	12.0	-	10.0	-	8.0	-	mA
		V_O = 1.5 V	15 V	24.0	-	20.0	-	16.0	-	mA
I_I	input leakage current	V_{DD} = 15 V	15 V	-	±0.3	-	±0.3	-	±1.0	μA
I_{DD}	supply current	I_O = 0 A	5 V	-	4.0	-	4.0	-	30	μA
			10 V	-	8.0	-	8.0	-	60	μA
			15 V	-	16.0	-	16.0	-	120	μA
C_I	input capacitance			-	-	-	7.5	-	-	pF

11. Dynamic characteristics

Table 7. Dynamic characteristics
V_{SS} = 0 V; C_L = 50 pF; t_r = $t_f \leq$ 20 ns; T_{amb} = 25 °C; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula	Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	nA to nY; see Figure 5	5 V [1]	26 ns + (0.18 ns/pF)C_L	-	35	70	ns
			10 V	11 ns + (0.08 ns/pF)C_L	-	15	30	ns
			15 V	9 ns + (0.05 ns/pF)C_L	-	12	25	ns
t_{PLH}	LOW to HIGH propagation delay	nA to nY; see Figure 5	5 V [1]	23 ns + (0.55 ns/pF)C_L	-	50	100	ns
			10 V	14 ns + (0.23 ns/pF)C_L	-	25	50	ns
			15 V	12 ns + (0.16 ns/pF)C_L	-	20	40	ns
t_{THL}	HIGH to LOW output transition time	see Figure 5	5 V [1]	3 ns + (0.35 ns/pF)C_L	-	20	40	ns
			10 V	3 ns + (0.14 ns/pF)C_L	-	10	20	ns
			15 V	2 ns + (0.09 ns/pF)C_L	-	7	14	ns
t_{TLH}	LOW to HIGH output transition time	see Figure 5	5 V [1]	10 ns + (1.00 ns/pF)C_L	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C_L	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C_L	-	20	40	ns

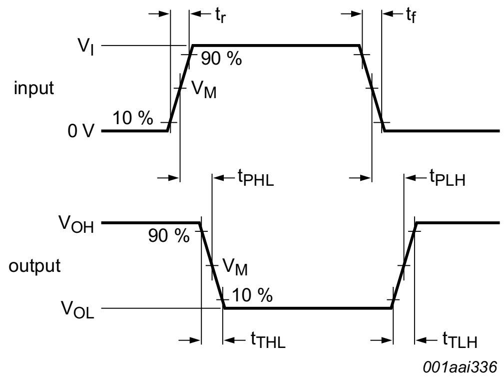
[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown (C_L in pF).

Table 8. Dynamic power dissipation P_D

P_D can be calculated from the formulas shown. V_{SS} = 0 V; $t_r = t_f \leq 20$ ns; T_{amb} = 25 °C.

Symbol	Parameter	V_{DD}	Typical formula for P_D (μW)	where:
P_D	dynamic power dissipation	5 V	$P_D = 2500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f_i = input frequency in MHz;
		10 V	$P_D = 11000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f_o = output frequency in MHz;
		15 V	$P_D = 35000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	C_L = output load capacitance in pF;
				V_{DD} = supply voltage in V;
				$\Sigma(f_o \times C_L)$ = sum of the outputs.

12. Waveforms



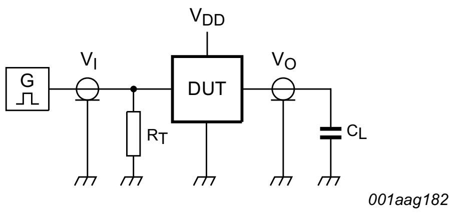
Measurement points are given in Table 9.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 5. Input (nA) to output (nY) propagation delays and transition times

Table 9. Measurement points

Input		Output		
V_M	V_I	V_M	V_X	V_Y
$0.5V_{DD}$	0 V to V_{DD}	$0.5V_{DD}$	$0.1V_{DD}$	$0.9V_{DD}$



Test data is given in Table 10.

Definitions for test circuit:

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

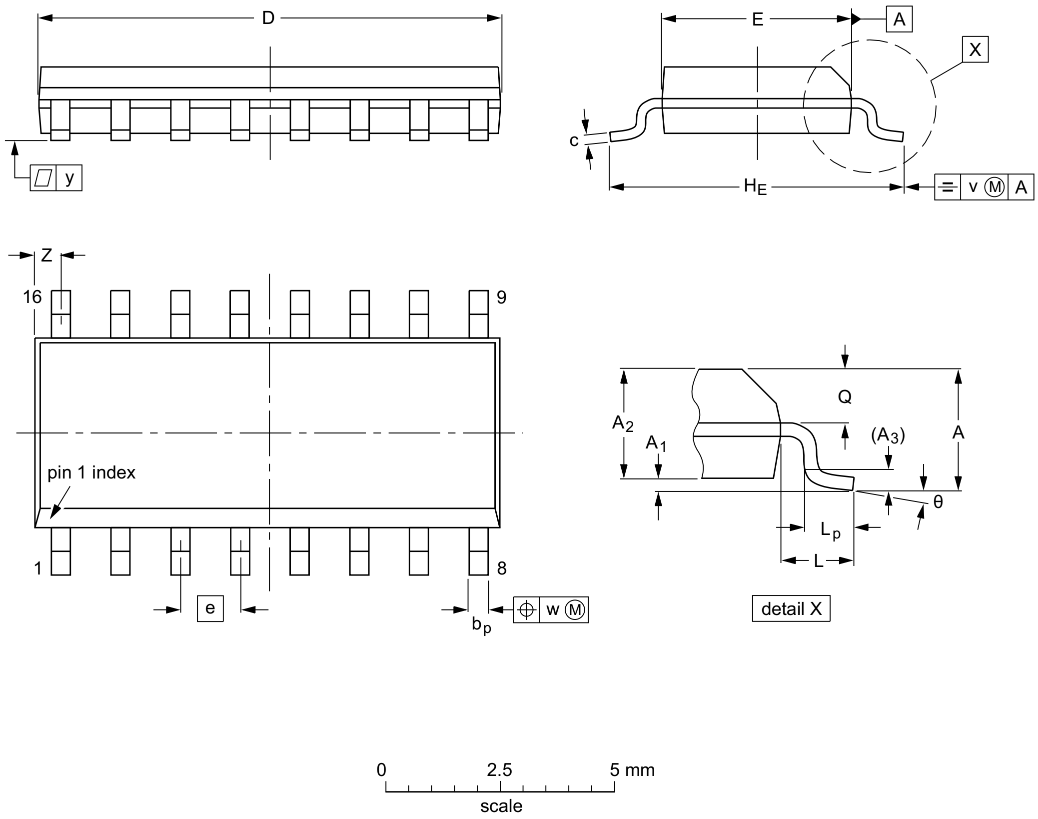
Fig 6. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Input			Load
V_{DD}	V_I	V_M	t_r, t_f	C_L
5 V to 15 V	V_{DD}	$0.5V_I$	≤ 20 ns	50 pF

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D(1)	E(1)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 7. Package outline SOT109-1 (SO16)

14. Abbreviations

Table 11. Abbreviations

Acronym	Description
DTL	Diode Transistor Logic
DUT	Device Under Test
LOCMOS	Local Oxidation CMOS
TTL	Transistor Transistor Logic

15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4049B v.10	20160324	Product data sheet	-	HEF4049B v.9
Modifications:	• Type number HEF4049BP (SOT38-4) removed.			
HEF4049B v.9	20111118	Product data sheet	-	HEF4049B v.8
Modifications:	• Table 6: I_{OH} minimum values changed to maximum • Table 11: Added DUT			
HEF4049B v.8	20091202	Product data sheet	-	HEF4049B v.7
HEF4049B v.7	20090721	Product data sheet	-	HEF4049B v.6
HEF4049B v.6	20090325	Product data sheet	-	HEF4049B v.5
HEF4049B v.5	20081111	Product data sheet	-	HEF4049B v.4
HEF4049B v.4	20080704	Product data sheet	-	HEF4049B_CNV v.3
HEF4049B_CNV v.3	19950101	Product specification	-	HEF4049B_CNV v.2
HEF4049B_CNV v.2	19950101	Product specification	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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18. Contents

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